

C1210X302GATACTU

Aliases (C1210X302GATAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 3,000 pF, 2%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information				
Series	SMD Comm X8G HT150C Flex			
Style	SMD Chip			
Description	SMD, MLCC, High Temperature, Ultra-Stable			
Features	High Temperature, Ultra-Stable			
RoHS	Yes			
Termination	Flexible Termination No			
Marking				
AEC-Q200	No			
Typical Component Weight	40 mg			
Shelf Life	78 Weeks			
MSL	1			

Dimensions		
Chip Size	1210	
L	3.3mm +/-0.4mm	
W	2.6mm +/-0.3mm	
Т	1.1mm +/-0.15mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	

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Packaging Specifications	

Specifications		
Capacitance	3,000 pF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	2%	
Voltage DC	250 VDC	
Dielectric Withstanding Voltage	625 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

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Packaging	T&R, 180mm, Plastic Tape	Reference to +25 Applied (TCC)
Packaging Quantity	2500	, ,
		Dissipation Facto

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